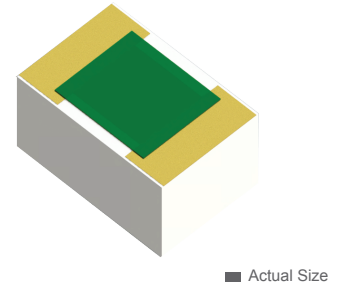


RM0805ZZ-XXXXWN-2T Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)

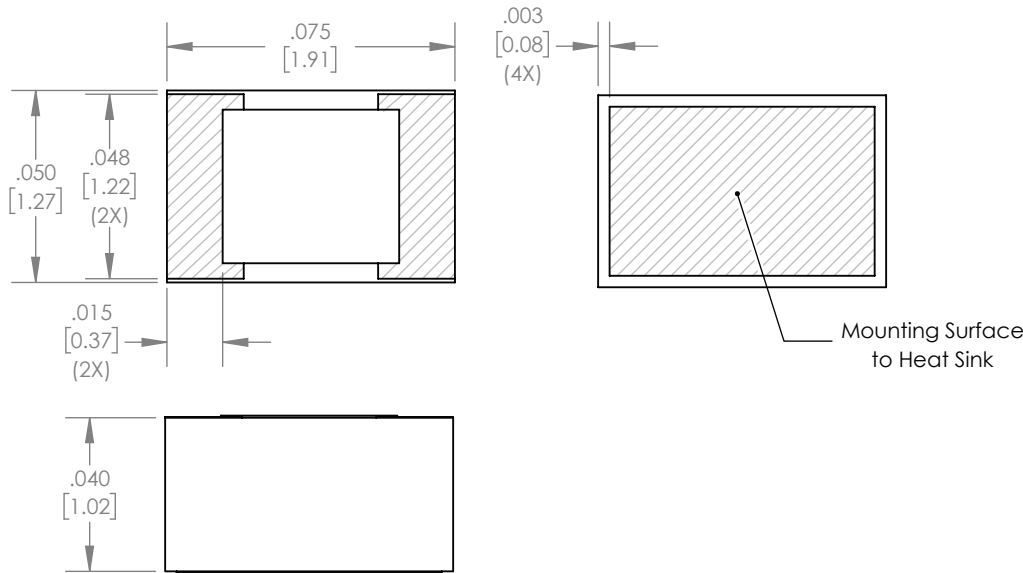


RM0805ZZ-XXXXWN-2T Parameters:

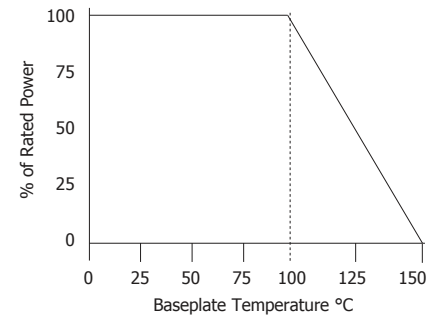
Resistance Range: 10Ω - 1kΩ
 Rated Power:* 5W
 Construction: Thick Film on 0.040" AlN
 Operating Temperature: -55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM0805ZZ-XXXXWN-2T Dimensions:



RM0805ZZ-XXXXWN-2T Power Derating Curve



Ordering Information:

Example Part Number: RM0805CC-50R0FN-2T

| | | | | | | | | | |
|---|------|----|---|---|---|---|---|------------------------------|---|
| RM | 0805 | ZZ | - | XXXX | W | N | - | 2T | UU |
| Prefix for Resistor w/ Single-Sided Terminals and Backplane | | | | Value Code 50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ | Tolerance F - 1% G - 2% J - 5% | Normal Inspection Contact factory for additional options | | Substrate 2T - 0.040" AlN | Packaging Blank - Bulk WP - Waffle Pack TR - Tape & Reel |
| Size 0805 | | | | | | | | | |

Terminal Metallization

| | |
|------|--|
| CB - | Tin Lead over Nickel over Silver |
| CC - | 100% Matte Tin over Copper over Silver |
| CT - | 100% Matte Tin over Nickel over Silver |
| GA - | Gold |

| | RoHS | Magnetic | Solder | Epoxy | Wirebond |
|--|------|----------|--------|-------|----------|
| | No | Yes | Yes | No | No |
| | Yes | No | Yes | No | No |
| | Yes | Yes | Yes | No | No |
| | Yes | No | No | Yes | Yes |

Barry Industries reserves the right to change part number and/or process without notification.

RM0805ZZ-XXXXWN-2T Reliability Specifications:

| Parameter: | Test Condition: | Results: |
|--------------------------------|---|--|
| Short Time Overload | Apply 1.1x Rated Power for 5 Seconds. | ≤ 5.0% Resistance Shift |
| Rated Load Life | Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours | ≤ 5.0% Resistance Shift |
| Moisture Resistance | MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C | ≤ 5.0% Resistance Shift |
| Resistance to Soldering Heat | MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1 | ≤ 5.0% Resistance Shift |
| Resistance to Bonding Exposure | MIL-PRF-55342 Para 4.8.8.2 | ≤ 5.0% Resistance Shift |
| Solderability | MIL-PRF-55342 Para 4.8.12 | >95% Covered |
| High Temperature Storage | 125°C ±2°C for 500 Hours | 1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual) |
| Thermal Shock | -65 to +125 30 Minutes Dwell, 5 Cycles | 1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual) |

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